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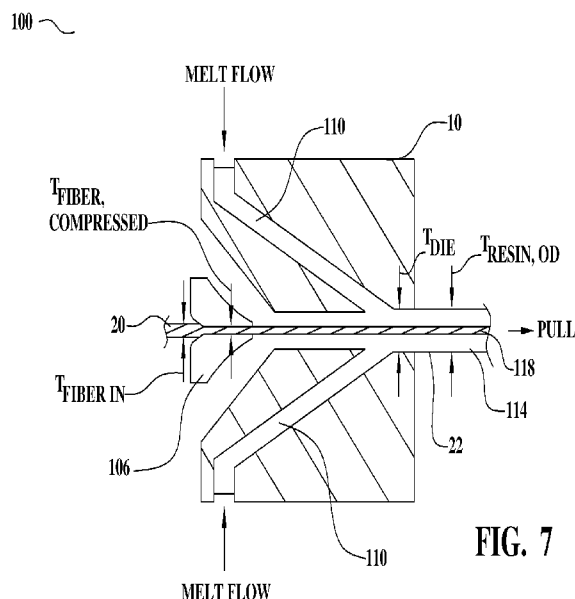


FIG. 7

(57) Abstract: A method to form moldable capsules of a conductively doped resin-based material are created. A resin-based material is extruded/pultruded onto a bundle of conductive material. The resin-based material and the bundle are sectioned into moldable capsules. The method further comprises heating the bundle to a temperature near the melt temperature of the resin-based material. The heating may comprise heating the bundle to a temperature above the melt temperature of the resin-based material. In further embodiments, heating comprises heating the bundle to a temperature above the glass transition temperature of the resin-based material.